

## LED Driver with Average-Mode Constant Current Control

### Features

- Fast Average Current Control
- Programmable Constant Off-Time Switching
- PWM/Linear Dimming Input
- Output Short Circuit Protection with Skip Mode
- Ambient Operating Temperature -40°C to +125°C
- Pin-Compatible with the HV9910B and HV9961

### Applications

- DC/DC or AC/DC LED Driver Applications
- LED Back-Light Driver for LCD Displays
- General Purpose Constant Current Source
- LED Signage and Displays
- Architectural and Decorative LED Lighting
- LED Street Lighting

### Description

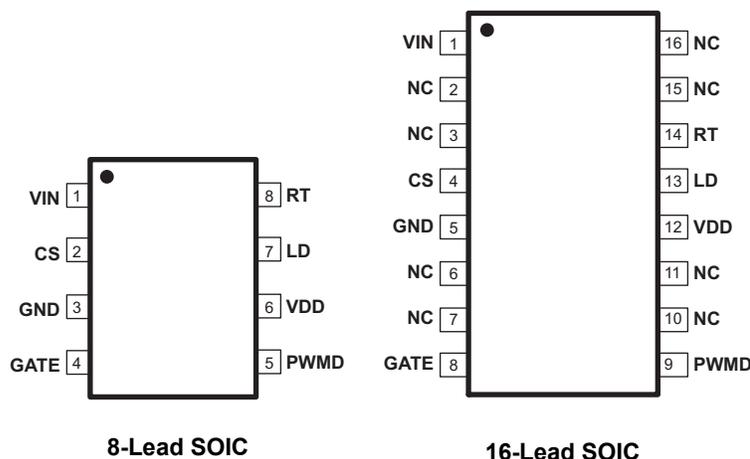
HV9861A is a patented, average-mode, constant-current control, LED driver IC operating in a constant off-time mode. Unlike the HV9910B, this control IC does not produce a peak-to-average error, which therefore greatly improves the accuracy, line and load regulation of the LED current without any need for loop compensation or high-side current sensing. The output LED current accuracy is  $\pm 3\%$ .

The IC is equipped with a current limit comparator for hiccup-mode output short circuit protection. Internal over-temperature protection is provided. The internally regulated voltage ( $V_{DD}$ ) for the HV9861A is 7.5V.

The IC can be powered from a 15 - 450V supply. A PWM dimming input is provided that accepts an external control TTL-compatible signal. The output current can be programmed by an internal 270 mV reference, or controlled externally through a 0 - 1.5V dimming input.

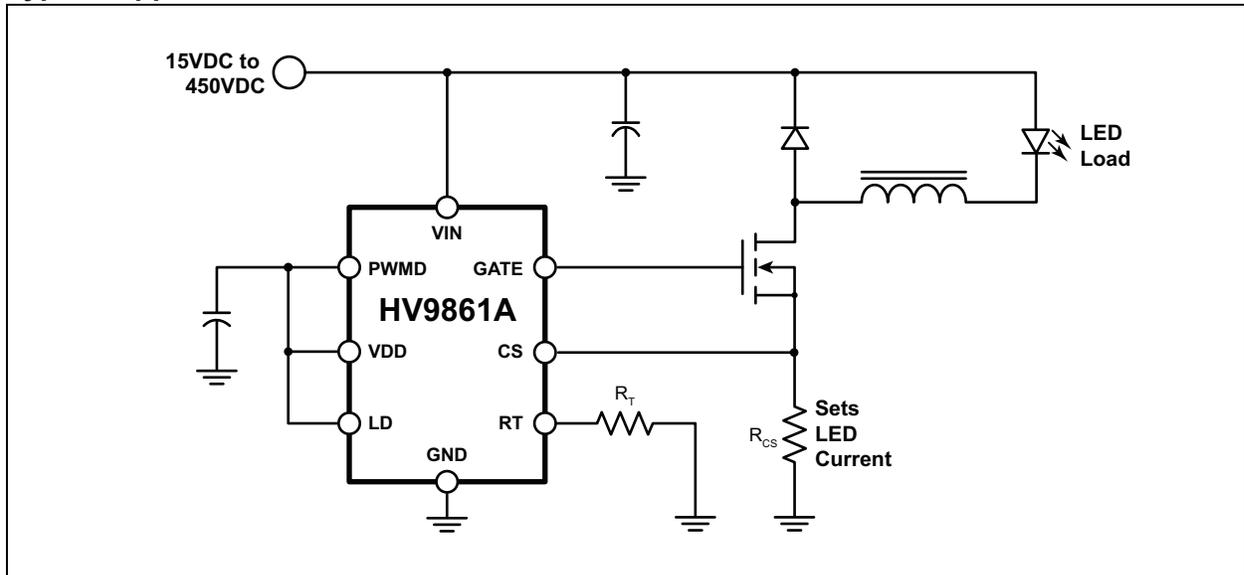
HV9861A is pin-to-pin compatible with the HV9910B and HV9961, and can be used as a drop-in replacement for many applications to improve the LED current accuracy and regulation.

### Package Types

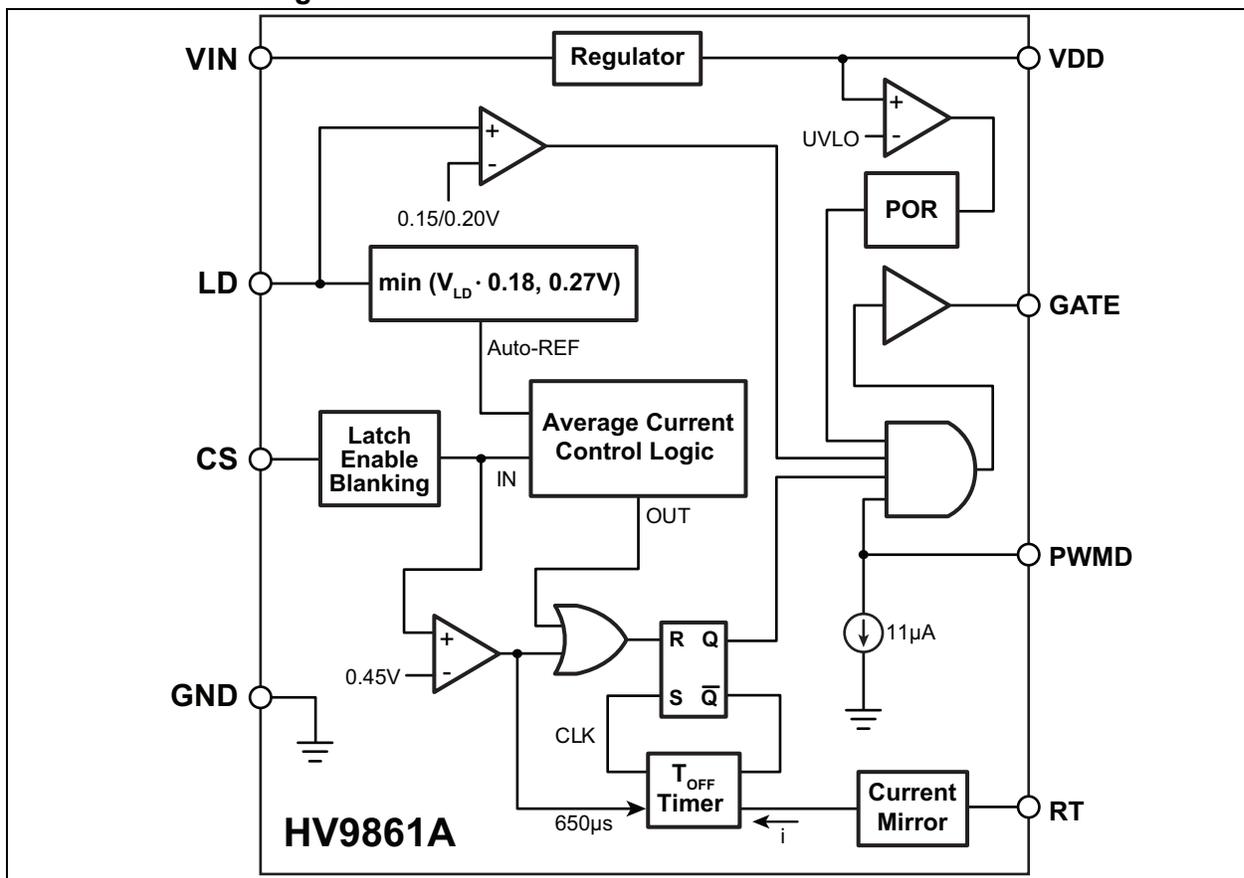


See [Table 2-1](#) for pin information

## Typical Application Circuit



## Functional Block Diagram



## 1.0 ELECTRICAL CHARACTERISTICS

### ABSOLUTE MAXIMUM RATINGS

|  |                              |
|--|------------------------------|
| $V_{IN}$ to GND.....                                       | -0.5V to +470V               |
| $V_{DD}$ to GND.....                                       | 12V                          |
| LD, PWMD, GATE to GND.....                                 | -0.3V to ( $V_{DD} + 0.3V$ ) |
| CS, RT to GND .....  | -0.3V to 5.0V                |
| Operating temperature.....                                 | -40°C to +125°C              |
| Storage temperature .....                                  | -65°C to +150°C              |
| Continuous power dissipation ( $T_A = +25^\circ\text{C}$ ) |                              |
| 8-lead SOIC.....   | 650 mW                       |
| 16-lead SOIC.....  | 1000 mW                      |

**Note:** Stresses above those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions, above those indicated in the operational listings of this specification, is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

### 1.1 ELECTRICAL SPECIFICATIONS

**TABLE 1-1: ELECTRICAL CHARACTERISTICS (Note 1)**

| Parameter                                 | Symbol                       | Min  | Typ  | Max  | Units         | Conditions   |
|---|------------------------------|------|------|------|---------------|--|
| <b>Input</b>                              |                              |      |      |      |               |  |
| Input DC Supply Voltage Range (Note 2)    | $V_{INDC}$                   | 15   | —    | 450  | V             | DC Input Voltage (Note 3)  |
| Shut-down Mode Supply Current             | $I_{INSD}$                   | —    | 0.5  | 1.1  | mA            | Pin PWMD to GND (Note 3)   |
| <b>Internal Regulator</b>                 |                              |      |      |      |               |  |
| Internally Regulated Voltage              | $V_{DD}$                     | 7.25 | 7.50 | 8.20 | V             | 500 pF at GATE; $R_T = 226\text{ k}\Omega$   |
| Line Regulation of $V_{DD}$               | $\Delta V_{DD, \text{line}}$ | —    | —    | 1    | V             | $V_{IN} = 15 - 450V$ ,<br>500 pF at GATE; $R_T = 226\text{ k}\Omega$                   |
| Load Regulation of $V_{DD}$               | $\Delta V_{DD, \text{load}}$ | —    | —    | 100  | mV            | $I_{DD(\text{ext})} = 0 - 1\text{ mA}$ ,<br>500 pF at GATE; $R_T = 226\text{ k}\Omega$ |
| $V_{DD}$ Under-voltage Lockout Threshold  | UVLO                         | 6.45 | —    | —    | V             | $V_{IN}$ rising (Note 3)   |
| $V_{DD}$ Under-voltage Lockout Hysteresis | $\Delta UVLO$                | —    | 500  | —    | mV            | $V_{IN}$ falling   |
| $V_{DD}$ Voltage Margin                   | $\Delta V_{DD(UV)}$          | 500  | —    | —    | mV            | $\Delta V_{DD(UV)} = V_{DD} - UVLO$ (Note 3)   |
| Maximum Input Current (limited by UVLO)   | $I_{IN,MAX}$                 | 3.5  | —    | —    | mA            | $V_{IN} = 15V$ , $T_A = 25^\circ\text{C}$ (Note 4)                                     |
|   |                              | 1.5  | —    | —    |               | $V_{IN} = 15V$ , $T_A = 125^\circ\text{C}$ (Note 4)                                    |
| <b>PWM Dimming</b>                        |                              |      |      |      |               |  |
| PWMD Input Low Voltage                    | $V_{EN(lo)}$                 | —    | —    | 0.8  | V             | $V_{IN} = 15 - 450V$ (Note 3)  |
| PWMD Input High Voltage                   | $V_{EN(hi)}$                 | 2.2  | —    | —    | V             | $V_{IN} = 15 - 450V$ (Note 3)  |
| Internal Pull-down Current at PWMD        | $I_{EN}$                     | 8    | —    | 15   | $\mu\text{A}$ | $V_{PWMD} = 0.8V$  |

**TABLE 1-1: ELECTRICAL CHARACTERISTICS (CONTINUED)(Note 1)**

| Parameter                           | Symbol                     | Min   | Typ | Max   | Units              | Conditions   |
|-------------------------------------|----------------------------|-------|-----|-------|--------------------|--|
| <b>Average Current Sense Logic</b>  |                            |       |     |       |                    |  |
| Current Sense Reference Voltage     | $V_{CSST}$                 | 262   | —   | 280   | mV                 |  |
| LD-to-CS Voltage Ratio              | $A_{V(LD)}$                | 0.175 | —   | 0.182 | —                  |  |
| LD-to-CS Voltage Offset             | $A_V \cdot V_{LD(OFFSET)}$ | -15   | —   | 12    | mV                 | $V_{OFFSET} = V_{CS} - (A_{V(LD)} \cdot V_{LD})$ ;<br>$V_{LD} = 1.2V$              |
| CS Threshold Temperature Regulation | $\Delta V_{CS(TEMP)}$      | —     | —   | 5     | mV                 | <b>Note 4</b>  |
| LD Input Voltage, Shutdown          | $V_{LD(OFF)}$              | —     | 150 | —     | mV                 | $V_{LD}$ falling   |
| LD Input Voltage, Enable            | $V_{LD(EN)}$               | —     | 200 | —     | mV                 | $V_{LD}$ rising  |
| Current Sense Blanking Interval     | $T_{BLANK}$                | 140   | —   | 290   | ns                 | <b>Note 3</b>  |
| Minimum On-time                     | $T_{ON(MIN)}$              | —     | —   | 760   | ns                 | $V_{CS} = V_{CSST} + 30\text{ mV}$   |
| Maximum Steady-state Duty Cycle     | $D_{MAX}$                  | 80    | —   | —     | %                  | Reduction in output LED current may occur beyond this duty cycle ( <b>Note 1</b> ) |
| <b>Short Circuit Protection</b>     |                            |       |     |       |                    |  |
| Hiccup Threshold Voltage            | $V_{CSH}$                  | 410   | —   | 510   | mV                 | <b>Note 3</b>  |
| Current Limit Delay CS-to-GATE      | $T_{DELAY}$                | —     | —   | 150   | ns                 | $V_{CS} = V_{CSH} + 30\text{ mV}$  |
| Short Circuit Hiccup Time           | $T_{HICCUP}$               | 400   | —   | 850   | $\mu\text{s}$      |  |
| Minimum On-time (Short Circuit)     | $T_{ON(MIN)SC}$            | —     | —   | 430   | ns                 | $V_{CS} = 4V$  |
| <b>TOFF Timer</b>                   |                            |       |     |       |                    |  |
| Off-time                            | $T_{OFF}$                  | 32    | 40  | 48    | $\mu\text{s}$      | $R_T = 1\text{ M}\Omega$   |
|                                     |                            | 8     | 10  | 12    |                    | $R_T = 226\text{ k}\Omega$   |
| <b>GATE Driver</b>                  |                            |       |     |       |                    |  |
| Sourcing Current                    | $I_{SOURCE}$               | 0.165 | —   | —     | A                  | $V_{GATE} = 0V, V_{DD} = 7.5V$   |
| Sinking Current                     | $I_{SINK}$                 | 0.165 | —   | —     | A                  | $V_{GATE} = V_{DD}, V_{DD} = 7.5V$   |
| Output Rise Time                    | $t_{RISE}$                 | —     | 30  | 50    | ns                 | $C_{GATE} = 500\text{ pF}, V_{DD} = 7.5V$  |
| Output Fall Time                    | $t_{FALL}$                 | —     | 30  | 50    | ns                 | $C_{GATE} = 500\text{ pF}, V_{DD} = 7.5V$  |
| <b>Over-Temperature Protection</b>  |                            |       |     |       |                    |  |
| Shut-down Temperature               | $T_{SD}$                   | 128   | 140 | —     | $^{\circ}\text{C}$ | <b>Note 4</b>  |
| Hysteresis                          | $\Delta T_{SD}$            | —     | 20  | —     | $^{\circ}\text{C}$ | <b>Note 4</b>  |

**Note 1:** Specifications apply at  $T_A = 25^{\circ}\text{C}$ ,  $V_{IN} = 15V$ ,  $V_{LD} = V_{DD}$ ,  $PWMD = V_{DD}$  unless otherwise noted.

**2:** Also limited by package-power dissipation limit; Whichever is lower.

**3:** Applies over the full operating ambient temperature range of  $-40^{\circ}\text{C} < T_A < +125^{\circ}\text{C}$ .

**4:** For design guidance only.

**TABLE 1-2: THERMAL RESISTANCE**

| Package      | Symbol        | Min | Typ | Max | Units                | Conditions |
|--------------|---------------|-----|-----|-----|----------------------|------------|
| 8-Lead SOIC  | $\theta_{JA}$ | —   | 101 | —   | $^{\circ}\text{C/W}$ |            |
| 16-Lead SOIC | $\theta_{JA}$ | —   | 83  | —   | $^{\circ}\text{C/W}$ |            |

## 2.0 PIN DESCRIPTION

The details on the pins of HV9861A are listed on [Table 2-1](#). Refer to [Package Types](#) for the location of pins.

**TABLE 2-1: PIN DESCRIPTION**

| Pin #       |                            | Function | Description  |
|-------------|----------------------------|----------|--|
| 8-Lead SOIC | 16-Lead SOIC               |          |  |
| 1           | 1                          | VIN      | Input of a 15 - 450V linear regulator.   |
| 2           | 4                          | CS       | Current sense pin used to sense the FET current by means of an external sense resistor.  |
| 3           | 5                          | GND      | Ground return for all internal circuitry. This pin must be electrically connected to the ground of the power train.  |
| 4           | 8                          | GATE     | Output GATE driver for an external N-channel power MOSFET.   |
| 5           | 9                          | PWMD     | PWM-dimming input of the IC. When this pin is pulled to GND, the gate driver is turned off. When the pin is pulled high, the gate driver operates normally.  |
| 6           | 12                         | VDD      | Power supply pin for all internal circuits. It must be bypassed with a low-ESR capacitor to GND (at least 0.1 $\mu$ F).  |
| 7           | 13                         | LD       | Linear-dimming input. Sets the current sense threshold as long as the voltage at this pin is less than 1.5V. If voltage at LD falls below 150 mV, the GATE output is disabled. The GATE signal recovers at 200 mV at LD. |
| 8           | 14                         | RT       | A resistor connected between this pin and GND programs the GATE off-time.  |
| -           | 2, 3, 6, 7, 10, 11, 15, 16 | NC       | No connection.   |

## 3.0 APPLICATION INFORMATION

Peak-current control (as in the HV9910B) of a buck converter is the most economical and simple way to regulate its output current. However, this method suffers accuracy and regulation problems that arise from the so-called peak-to-average current error, contributed to by the current ripple in the output inductor and the propagation delay in the current-sense comparator. The full inductor-current signal is unavailable for direct sensing at the ground potential in a buck converter when the control switch is referenced to the same ground potential. While it is very simple to detect the peak current in the switch, controlling the average inductor current is usually implemented by level translating the sense signal from the positive supply rail. Though this is practical for relatively low input voltage, this type of average-current control may become excessively complex and expensive in off line AC or other high-voltage DC applications.

HV9861A employs a patented control scheme, achieving fast and very accurate control of average current in the buck inductor through sensing the switch current only. No compensation of the current-control loop is required. The LED current response to PWM input is similar to that of the HV9910B. The inductor-current ripple amplitude does not affect this control scheme significantly. Therefore, the LED current is independent of the variation in inductance, switching frequency, or output voltage. Constant off-time control of the buck converter is used for stability and to improve the LED-current regulation over a wide range of input voltages. (Note that, unlike the HV9910B, this IC does not support the constant-frequency mode of operation.)

### 3.1 OFF Timer

The timing resistor connected to RT determines the off-time of the gate driver, and it must be wired to GND. Wiring this resistor to GATE as with the HV9910B is no longer supported. The equation governing the off-time of the GATE output is given by:

$$T_{OFF}(\mu s) = \frac{R_T(k\Omega)}{25} + 0.3$$

Within the range of  $30\text{ k}\Omega \leq R_T \leq 1.0\text{ M}\Omega$ .

### 3.2 Average Current Control Feedback and Output Short Circuit Protection

The current through the switching MOSFET source is averaged and used to give constant-current feedback. This current is detected using a sense resistor at the CS pin. The feedback operates in a fast open-loop mode. No compensation is required. Output current is programmed simply as:

$$I_{LED} = \frac{0.27V}{R_{CS}}$$

When the voltage at the LD input  $V_{LD} \geq 1.5V$ . Otherwise:

$$I_{LED} = \frac{V_{LD} \cdot 0.18}{R_{CS}}$$

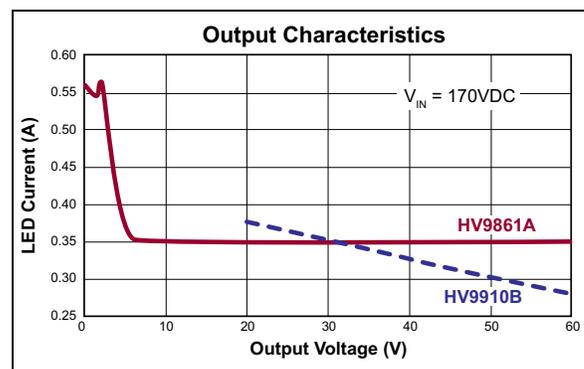
The above equations are only valid for continuous conduction of the output inductor. It is a good practice to design the inductor such that the switching peak-to-peak ripple current in it is 30~40% of its average DC full-load current. Hence, the recommended inductance can be calculated as:

$$L = \frac{V_{O(MAX)} \cdot T_{OFF}}{0.4 \cdot I_{O(MAX)}}$$

The duty-cycle range of the current control feedback is limited to  $D \leq 0.8$ . A reduction in the LED current may occur when the LED string voltage  $V_O$  is greater than 80% of the input voltage  $V_{IN}$  of the HV9861A LED driver.

Reducing the output LED voltage  $V_O$  below  $V_{O(MIN)} = V_{IN} \cdot D_{MIN}$ , where  $D_{MIN} = 760\text{ ns}/(T_{OFF} + 760\text{ ns})$ , may also result in the loss of regulation of the LED current. However, this condition causes an increase in the LED current and can potentially trip the short-circuit protection comparator.

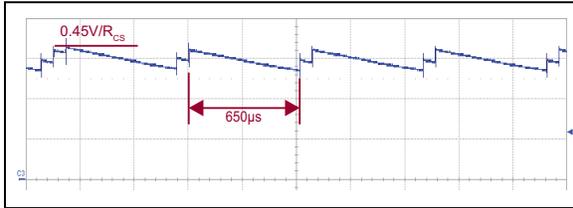
A typical output characteristic of the HV9861A LED driver is shown in Figure 3-1. The corresponding HV9910B characteristic is given for comparison.



**FIGURE 3-1:** Typical Output Characteristic of an HV9861A LED Driver.

The short circuit protection comparator trips when the voltage at CS exceeds 0.45V. When this occurs, the GATE off-time  $T_{HICCUP} = 650\ \mu s$  is generated to prevent stair-casing of the inductor current, and potentially

its saturation, due to insufficient output voltage. The typical short-circuit current is shown in the waveform of Figure 3-2.

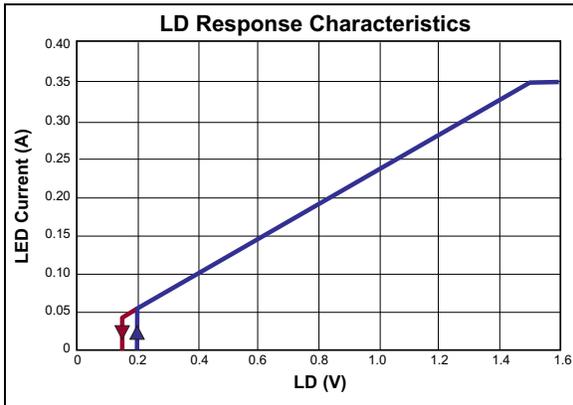


**FIGURE 3-2:** Short-circuit Inductor Current.

A leading-edge blanking delay is provided at CS to prevent false triggering of the current feedback and the short circuit protection.

### 3.3 Linear Dimming

When the voltage at LD falls below 1.5V, the internal 270 mV reference to the constant-current feedback becomes overridden by  $V_{LD} \cdot 0.18$ . As long as the current in the inductor remains continuous, the LED current is given by the equation in Section 3.2 “Average Current Control Feedback and Output Short Circuit Protection”. However, when  $V_{LD}$  falls below 150mV, the GATE output becomes disabled. The GATE signal recovers, when  $V_{LD}$  exceeds 200 mV. This is required in some applications to be able to shut the LED lamp off with the same signal input that controls the brightness. The typical linear dimming response is shown in Figure 3-3.



**FIGURE 3-3:** Typical Linear Dimming Response of an HV9861A LED Driver.

The linear dimming input could also be used for “mixed-mode” dimming to expand the dimming ratio. In such case a pulse-width modulated signal of a measured amplitude below 1.5V should be applied at LD.

### 3.4 Input Voltage Regulator

HV9861A can be powered directly from a 15 - 450VDC supply through its VIN input. When this voltage is applied at the VIN pin, the HV9861A maintains a constant 7.5V level at VDD. This voltage can be used to power the IC and external circuitry connected to VDD within the rated maximum current or within the thermal ratings of the package, whichever limit is lower. The VDD pin must be bypassed by a low ESR capacitor to provide a low impedance path for the high frequency current of the GATE output. The HV9861A can also be powered through the VDD pin directly with a voltage greater than the internally regulated 7.5V, but less than 12V.

Despite the instantaneous voltage rating of 450V, continuous voltage at VIN is limited by the power dissipation in the package. For example, when these ICs draw  $I_{IN} = 3.0$  mA from the VIN input, and the 8-lead SOIC package is used, the maximum continuous voltage at VIN is limited to the following:

$$V_{IN(MAX)} = \frac{T_{J(MAX)} - T_A}{R_{\theta,JA} \cdot I_{IN}} = 330V$$

In this instance, the ambient temperature  $T_A = 25^\circ C$ , the maximum working junction temperature  $T_{J(MAX)} = 125^\circ C$ , and the junction-to-ambient thermal resistance  $R_{\theta,JA} = 101^\circ C/W$ .

In such cases, when it is needed to operate the HV9861A from a higher voltage, a resistor or a Zener diode can be added in series with the VIN input to divert some of the power loss from the IC. In the above example, using a 100V Zener diode will allow the circuit to work up to 430V. The input current drawn from the VIN pin is represented by the following equation:

$$I_{IN} \approx 1.0mA + Q_G \cdot f_s$$

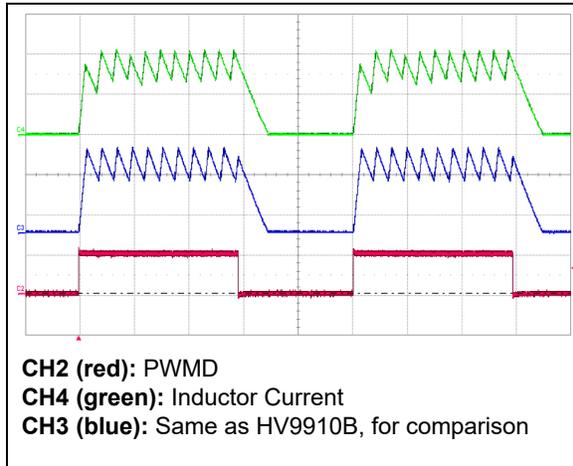
In the above equation,  $f_s$  is the switching frequency, and  $Q_G$  is the GATE charge of the external FET obtained from the manufacturer’s data sheet.

### 3.5 GATE Output

The GATE output of HV9861A is used to drive an external MOSFET. The gate charge,  $Q_G$ , of the external MOSFET should be less than 25 nC for switching frequencies  $\leq 100$  kHz and less than 15 nC for switching frequencies  $>100$  kHz.

## 3.6 PWM Dimming

Due to the fast open-loop response of the average-mode, current-control loop of the HV9861A, the PWM dimming performance nearly matches that of the HV9910B. The inductor current waveform comparison is shown in [Figure 3-4](#).



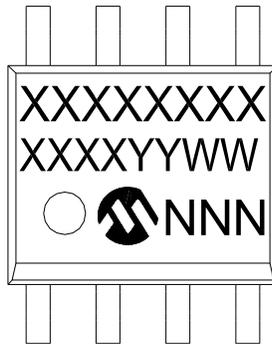
**FIGURE 3-4:** Typical PWM Dimming Response of an HV9861A LED Driver.

The rising and falling edges are limited by the current slew rate in the inductor. The first switching cycle is terminated upon reaching the 270 mV ( $V_{LD} \cdot 0.18$ ) level at CS. The circuit is further reaching its steady-state within 3–4 switching cycles regardless of the switching frequency.

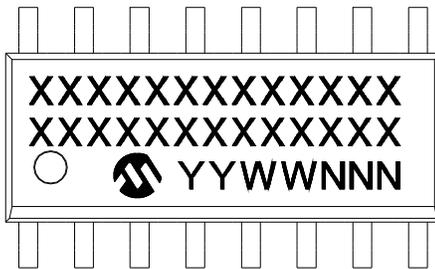
## 4.0 PACKAGING INFORMATION

### 4.1 Package Marking Information

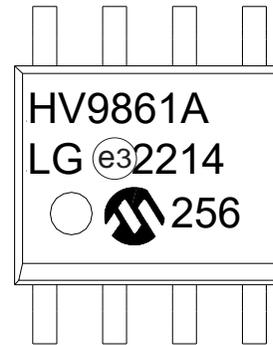
8-Lead SOIC



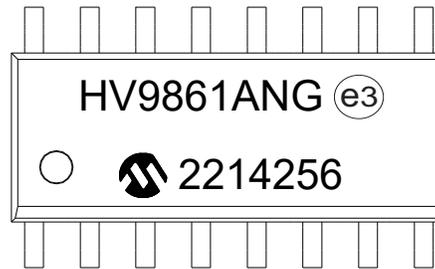
16-Lead SOIC



Example



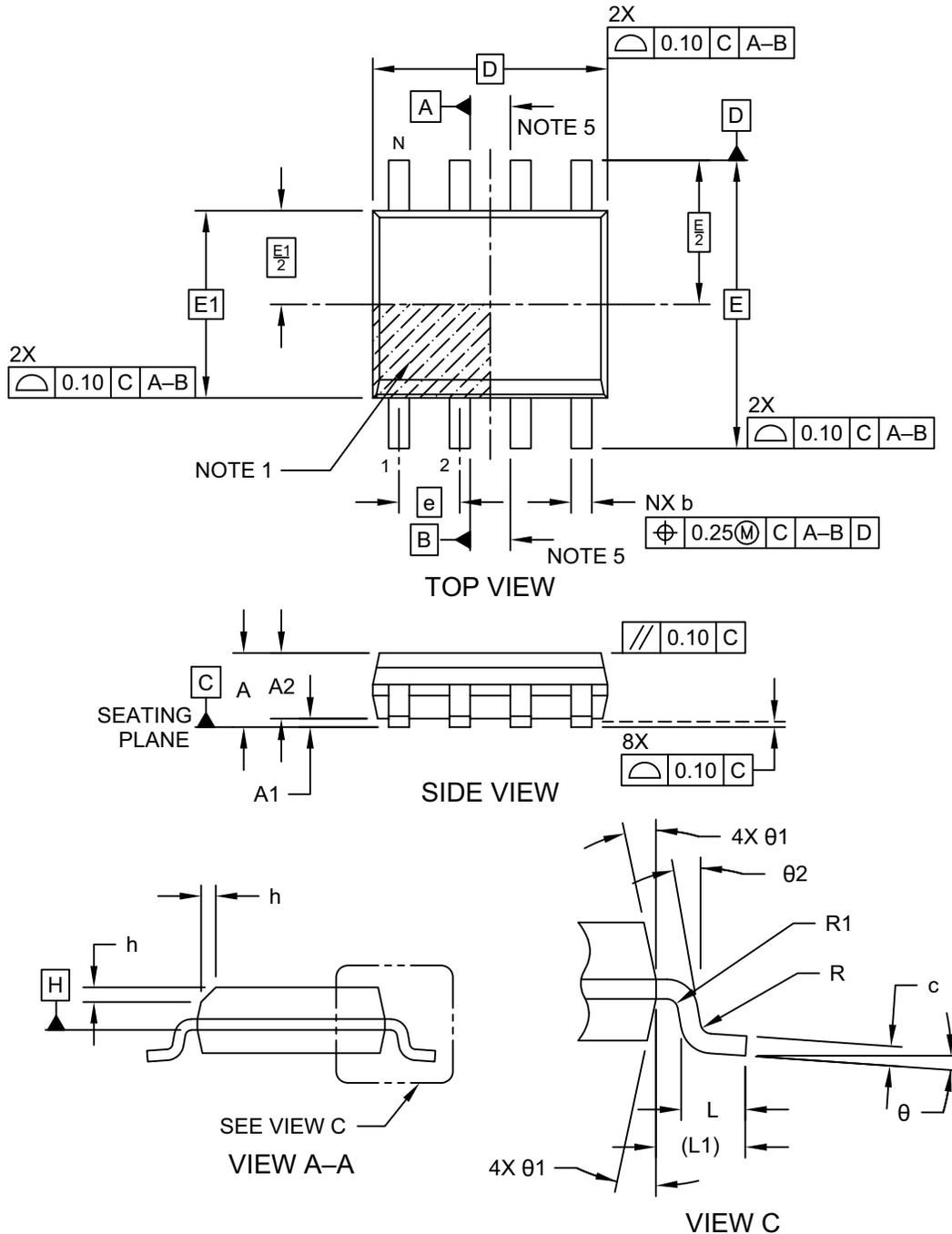
Example



|                |  |  |
|----------------|--|--|
| <b>Legend:</b> | XX...X   | Product code or customer-specific information  |
|                | Y  | Year code (last digit of calendar year)  |
|                | YY   | Year code (last 2 digits of calendar year)   |
|                | WW   | Week code (week of January 1 is week '01')   |
|                | NNN  | Alphanumeric traceability code   |
|                | e3   | Pb-free JEDEC® designator for Matte Tin (Sn)   |
|                | *  | This package is Pb-free. The Pb-free JEDEC designator (e3) can be found on the outer packaging for this package. |
|                | •, ▲, ▼  | Pin one index is identified by a dot, delta up, or delta down (triangle mark).                                   |
| <b>Note:</b>   | In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for customer-specific information. Package may or may not include the corporate logo. |  |
|                | Underbar ( _ ) and/or Overbar ( ¯ ) symbol may not be to scale.  |  |

## 8-Lead Plastic Small Outline (SN) - Narrow, 3.90 mm (.150 In.) Body [SOIC]

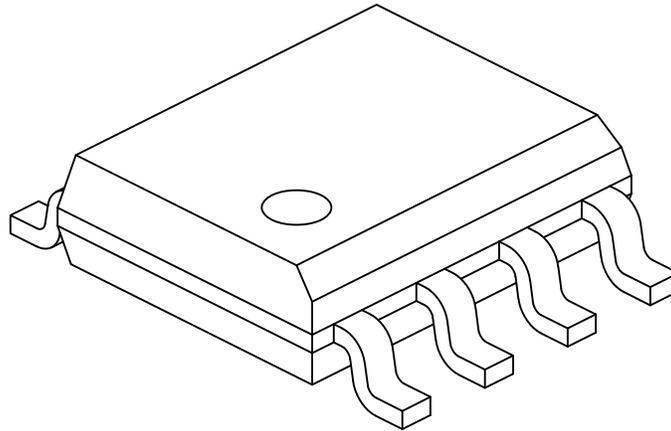
**Note:** For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



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## 8-Lead Plastic Small Outline (SN) - Narrow, 3.90 mm (.150 In.) Body [SOIC]

**Note:** For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



| Dimension Limits         | Units | MILLIMETERS |     |      |
|--------------------------|-------|-------------|-----|------|
|                          |       | MIN         | NOM | MAX  |
| Number of Pins           | N     | 8           |     |      |
| Pitch                    | e     | 1.27 BSC    |     |      |
| Overall Height           | A     | –           | –   | 1.75 |
| Molded Package Thickness | A2    | 1.25        | –   | –    |
| Standoff §               | A1    | 0.10        | –   | 0.25 |
| Overall Width            | E     | 6.00 BSC    |     |      |
| Molded Package Width     | E1    | 3.90 BSC    |     |      |
| Overall Length           | D     | 4.90 BSC    |     |      |
| Chamfer (Optional)       | h     | 0.25        | –   | 0.50 |
| Foot Length              | L     | 0.40        | –   | 1.27 |
| Footprint                | L1    | 1.04 REF    |     |      |
| Lead Thickness           | c     | 0.17        | –   | 0.25 |
| Lead Width               | b     | 0.31        | –   | 0.51 |
| Lead Bend Radius         | R     | 0.07        | –   | –    |
| Lead Bend Radius         | R1    | 0.07        | –   | –    |
| Foot Angle               | θ     | 0°          | –   | 8°   |
| Mold Draft Angle         | θ1    | 5°          | –   | 15°  |
| Lead Angle               | θ2    | 0°          | –   | 8°   |

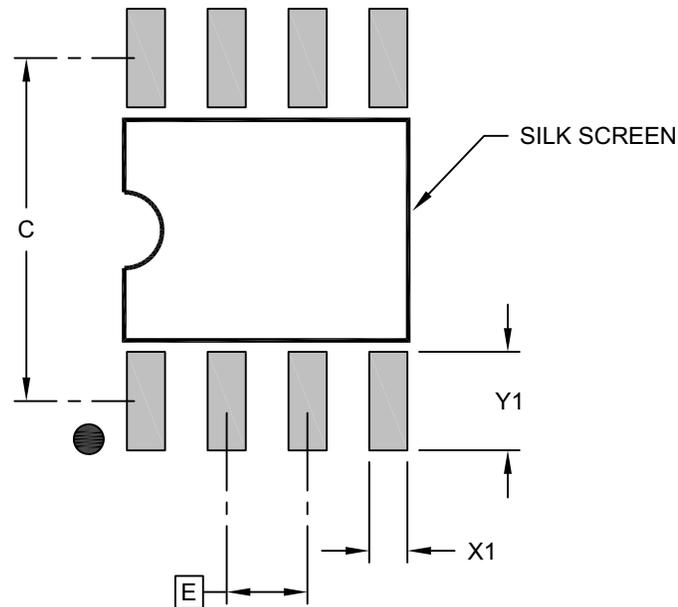
**Notes:**

- Pin 1 visual index feature may vary, but must be located within the hatched area.
- § Significant Characteristic
- Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.15mm per side.
- Dimensioning and tolerancing per ASME Y14.5M  
 BSC: Basic Dimension. Theoretically exact value shown without tolerances.  
 REF: Reference Dimension, usually without tolerance, for information purposes only.
- Datums A & B to be determined at Datum H.

Microchip Technology Drawing No. C04-057-SN Rev J Sheet 2 of 2

## 8-Lead Plastic Small Outline (SN) - Narrow, 3.90 mm (.150 In.) Body [SOIC]

**Note:** For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



### RECOMMENDED LAND PATTERN

| Dimension Limits        | Units | MILLIMETERS |      |      |
|-------------------------|-------|-------------|------|------|
|                         |       | MIN         | NOM  | MAX  |
| Contact Pitch           | E     | 1.27 BSC    |      |      |
| Contact Pad Spacing     | C     |             | 5.40 |      |
| Contact Pad Width (X8)  | X1    |             |      | 0.60 |
| Contact Pad Length (X8) | Y1    |             |      | 1.55 |

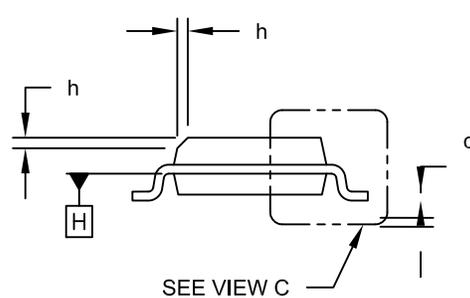
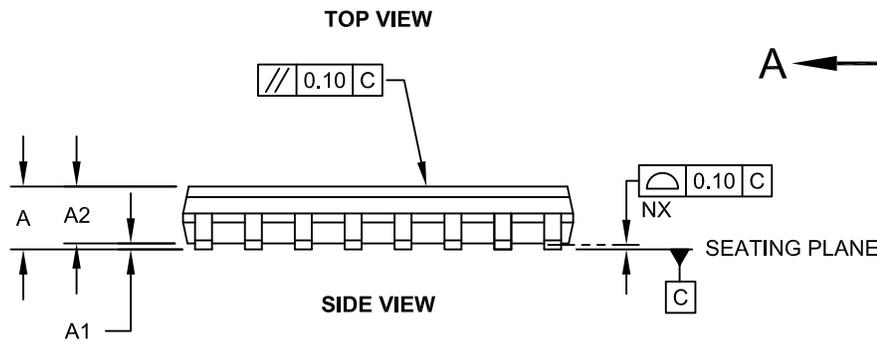
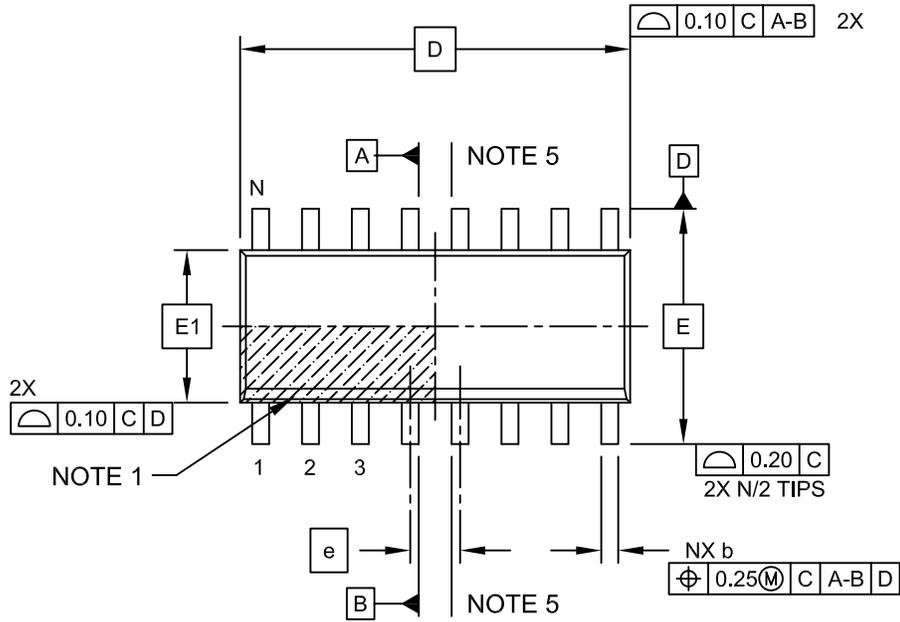
**Notes:**

1. Dimensioning and tolerancing per ASME Y14.5M  
BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing C04-2057-SN Rev J

## 16-Lead Plastic Small Outline (SL) - Narrow, 3.90 mm Body [SOIC]

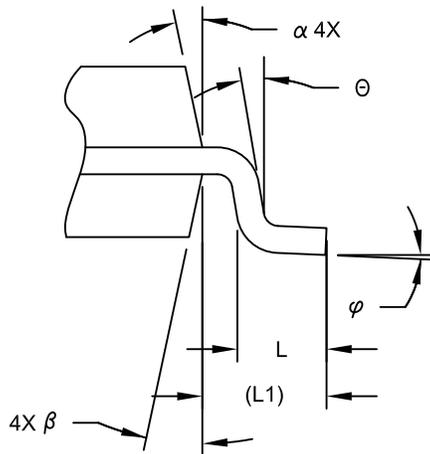
**Note:** For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



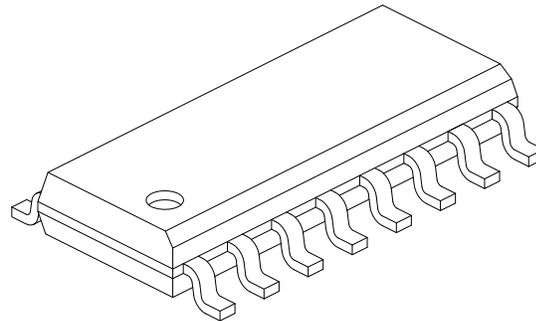
Microchip Technology Drawing No. C04-108C Sheet 1 of 2

## 16-Lead Plastic Small Outline (SL) - Narrow, 3.90 mm Body [SOIC]

**Note:** For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



VIEW C



| Dimension Limits         | Units | MILLIMETERS |     |      |
|--------------------------|-------|-------------|-----|------|
|                          |       | MIN         | NOM | MAX  |
| Number of Pins           | N     | 16          |     |      |
| Pitch                    | e     | 1.27 BSC    |     |      |
| Overall Height           | A     | -           | -   | 1.75 |
| Molded Package Thickness | A2    | 1.25        | -   | -    |
| Standoff §               | A1    | 0.10        | -   | 0.25 |
| Overall Width            | E     | 6.00 BSC    |     |      |
| Molded Package Width     | E1    | 3.90 BSC    |     |      |
| Overall Length           | D     | 9.90 BSC    |     |      |
| Chamfer (Optional)       | h     | 0.25        | -   | 0.50 |
| Foot Length              | L     | 0.40        | -   | 1.27 |
| Footprint                | L1    | 1.04 REF    |     |      |
| Lead Angle               | θ     | 0°          | -   | -    |
| Foot Angle               | φ     | 0°          | -   | 8°   |
| Lead Thickness           | c     | 0.10        | -   | 0.25 |
| Lead Width               | b     | 0.31        | -   | 0.51 |
| Mold Draft Angle Top     | α     | 5°          | -   | 15°  |
| Mold Draft Angle Bottom  | β     | 5°          | -   | 15°  |

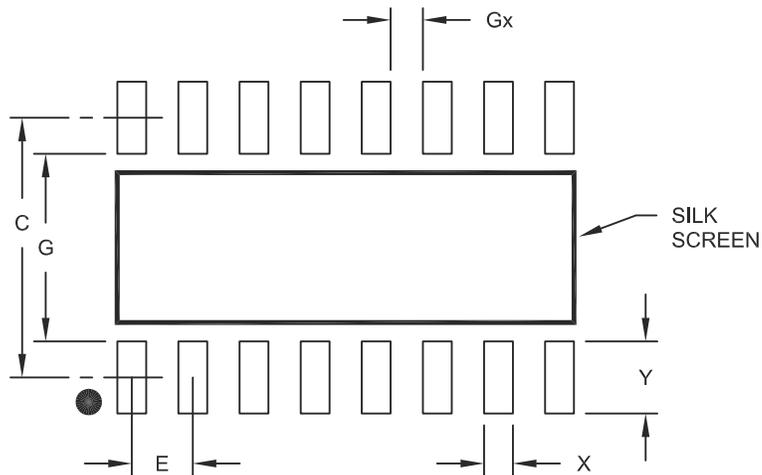
**Notes:**

- Pin 1 visual index feature may vary, but must be located within the hatched area.
- § Significant Characteristic
- Dimension D does not include mold flash, protrusions or gate burrs, which shall not exceed 0.15 mm per end. Dimension E1 does not include interlead flash or protrusion, which shall not exceed 0.25 mm per side.
- Dimensioning and tolerancing per ASME Y14.5M  
 BSC: Basic Dimension. Theoretically exact value shown without tolerances.  
 REF: Reference Dimension, usually without tolerance, for information purposes only.
- Datums A & B to be determined at Datum H.

Microchip Technology Drawing No. C04-108C Sheet 2 of 2

## 16-Lead Plastic Small Outline (SL) - Narrow, 3.90 mm Body [SOIC]

**Note:** For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



### RECOMMENDED LAND PATTERN

| Dimension Limits      | Units | MILLIMETERS |      |      |
|-----------------------|-------|-------------|------|------|
|                       |       | MIN         | NOM  | MAX  |
| Contact Pitch         | E     | 1.27 BSC    |      |      |
| Contact Pad Spacing   | C     |             | 5.40 |      |
| Contact Pad Width     | X     |             |      | 0.60 |
| Contact Pad Length    | Y     |             |      | 1.50 |
| Distance Between Pads | Gx    | 0.67        |      |      |
| Distance Between Pads | G     | 3.90        |      |      |

**Notes:**

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2108A

NOTES:

## APPENDIX A: REVISION HISTORY

### Revision B (July 2022)

- Updated the Electrical Characteristics table (Table 1-1).
- Updated [Section 4.0 “Packaging Information”](#) with the latest package drawings.
- Minor changes throughout the document.

### Revision A (December 2014)

- Original Release of this Document.

NOTES:

## PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, refer to the factory or the listed sales office.

| <u>PART NO.</u>  | <u>XX</u>   | - | <u>X</u>      | - | <u>X</u>   |
|--|---|---|---------------|---|------------|
| Device   | Package Options   |   | Environmental |   | Media Type |
| Device: HV9861A= LED Driver with Average-Mode Constant Current Control<br><br>Package: LG = 8-lead SOIC<br>NG = 16-lead SOIC<br><br>Environmental: G = Lead (Pb)-free/RoHS-compliant package<br><br>Media Type: (blank) = Reel for LG package, Tube for NG package | <b>Examples:</b><br><br>a) HV9861ALG-G: 8-lead SOIC package, Lead (Pb)-free, RoHS-compliant, 3300/Reel<br><br>b) HV9861ANG-G: 16-lead SOIC package, Lead (Pb)-free, RoHS-compliant, 45/Tube |   |               |   |            |

NOTES:

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ISBN: 978-1-6683-0861-5



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